

| L<br>Number | Hits  | Search Text  | DB  | Time stamp          |
|-------------|-------|--|---|---------------------|
| 1           | 4524  | sulfur same insulat\$  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:23 |
| 2           | 206   | (sulfur same insulat\$) same copper                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:24 |
| 3           | 50    | ((sulfur same insulat\$) same copper) and<br>magnetic            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:26 |
| 4           | 10    | ((sulfur same insulat\$) same copper) and<br>magnetic) and motor | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:29 |
| 5           | 19    | ((sulfur same insulat\$) same copper) and<br>magnetic) and coil  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:38 |
| 6           | 61605 | thermosetting adj resin  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:39 |
| 7           | 222   | (thermosetting adj resin) same sulfur                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>08:40 |
| 8           | 1     | ((thermosetting adj resin) same sulfur) same<br>insulation       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>09:07 |
| 9           | 4     | ("3391243"   "3356785"   "3324272"  <br>"3155787").PN.           | USPAT   | 2001/11/30<br>08:42 |
| 18          | 19    | 3652778.URPN.  | USPAT   | 2001/11/30<br>08:46 |
| 19          | 0     | ((thermosetting adj resin) same sulfur) same<br>coil             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2001/11/30<br>09:00 |

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| 20 | 2    | ((thermosetting adj resin) same sulfur) same wire                                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:02 |
| 21 | 2    | ((thermosetting adj resin) same sulfur) same conductor                           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:04 |
| 22 | 0    | ((thermosetting adj resin) same sulfur) and stator                               | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:04 |
| 23 | 7    | ((thermosetting adj resin) same sulfur) and rotor                                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:05 |
| 24 | 1    | ((thermosetting adj resin) same sulfur) and magnet                               | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:05 |
| 25 | 1432 | (thermosetting adj resin) same insulation  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:07 |
| 26 | 271  | ((thermosetting adj resin) same insulation) same (conductor or wire)             | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:07 |
| 27 | 40   | ((thermosetting adj resin) same insulation) same (conductor or wire)) and stator | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:31 |
| 28 | 868  | enamel same (high adj temperature)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:33 |
| 29 | 192  | (enamel same (high adj temperature)) same wire                                   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:34 |

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| 30 | 12    | ((enamel same (high adj temperature)) same wire) and stator                   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:57 |
| 31 | 255   | (thermosetting adj resin) same bobbin   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:57 |
| 32 | 5     | ((thermosetting adj resin) same bobbin) same stator                           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 09:58 |
| 37 | 206   | high adj temperature same solder adj layer                                    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:20 |
| 38 | 13    | (high adj temperature same solder adj layer) and thermosetting                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:22 |
| 39 | 34    | (high adj temperature same solder adj layer) and epoxy                        | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:15 |
| 40 | 68206 | high adj temperature same layer   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 13:32 |
| 41 | 2698  | (high adj temperature same layer) and thermosetting                           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:22 |
| 42 | 786   | ((high adj temperature same layer) and thermosetting) and wire                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:23 |
| 43 | 1046  | ((high adj temperature same layer) and thermosetting) and (wire or conductor) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30 12:25 |

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| 44 | 16   | ((high adj temperature same layer) and thermosetting) and (wire or conductor)) and stator   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>12:40 |
| 45 | 184  | ((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.                 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>12:43 |
| 46 | 1    | ((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.<br>) and solder | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>13:30 |
| 47 | 1    | ((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.<br>) and solder | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>13:30 |
| 48 | 275  | high adj temperature adj layer  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>13:33 |
| 51 | 800  | (310/208).CCLS.   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>13:56 |
| 52 | 18   | ((310/208).CCLS.) and solder  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>13:56 |
| 77 | 800  | (310/208).CCLS.   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>17:04 |
| 78 | 1058 | (310/43).CCLS.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2001/11/30<br>17:04 |